

## **AMENDMENTS TO THE CLAIMS**

1. (currently amended) A titanium copper alloy having excellent strength and bendability characterized in that; comprising it comprises 1.0 to 4.5% by mass of Ti, the balance of copper and inevitable impurities; wherein:

the diameter diameters of intermetallic compound particles consisting of Cu and Ti precipitated in the alloy is are 3  $\mu\text{m}$  or less;

the average number of said intermetallic compound particles having a diameter the diameters of 0.2 to 3  $\mu\text{m}$  is 700 or less per a cross-sectional area of 1000  $\mu\text{m}^2$  in a direction transverse direction to a rolling direction;

the average grain size measured in a cross-sectional area in a direction transverse direction to a rolling direction is 10  $\mu\text{m}$  or less; and

the alloy a tensile strength is 890 MPa or more.

2. (currently amended) The titanium copper alloy according to claim 1, wherein the average number of the intermetallic compound particles having the diameters a diameter of 0.2 to 3  $\mu\text{m}$  is 6 to 700 per a cross-sectional area of 1000  $\mu\text{m}^2$  in a direction transverse direction to a rolling direction.

3. (cancelled)

4. (currently amended) The A manufacturing method of the titanium copper alloy according to claim 3 7, wherein a the reduction ratio in the cold rolling between the solution treatment and the aging treatment is 50% or less.

5. (currently amended) The A manufacturing method of the titanium copper alloy according to claim 3 7, wherein the aging treatment is conducted at a temperature of 300 to 600°C.

6. (previously added) The A manufacturing method of the titanium copper alloy according to claim 4, wherein the aging treatment is conducted at a temperature of 300 to 600°C.

7. (new) A method of manufacturing the titanium copper alloy according to claim 1 or 2 comprising, in the following order:

heating a titanium copper alloy ingot at a temperature of 850 to 950°C for 30 minutes or more;

hot rolling the ingot, whereby the temperature at the end of the hot rolling is 700°C or more;

cold rolling the ingot;

conducting a solution treatment comprising annealing the ingot at a temperature in the range between (T-50)°C and (T+10)°C, and thereafter cooling the annealed material at a cooling rate of 100 °C/sec or more, wherein T is a temperature at which the solubility of Ti in Cu is equal to the concentration of Ti contained in the alloy;

cold rolling the alloy; and

conducting an aging treatment of the alloy.

### Remarks

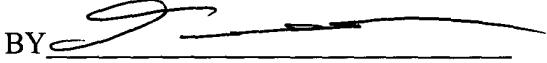
Claims 1-2 and 4-7 are pending in the application after entry of the herein amendment. The claims have been amended to more closely conform to US patent practice. Claim 3 has been cancelled and rewritten as new claim 7, to more closely conform to US patent practice.

Entry of the amendment and an early action on the merits is requested.

Respectfully submitted,

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